

# PATENT ASSIGNMENT

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Reinhold Bayerer	03/04/2011
Daniel Domes	03/04/2011
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Infineon Technologies AG
<b>Street Address:</b>	Am Campeon 1-12
<b>City:</b>	Neubiberg
<b>State/Country:</b>	GERMANY
<b>Postal Code:</b>	85579
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	13040348
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	5497-270
<b>NAME OF SUBMITTER:</b>	Mark R. Bilak
<b>Total Attachments: 1</b> source=5497-270_Assignment#page1.tif	

OP \$40.00 13040348

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**PATENT**  
**REEL: 026892 FRAME: 0897**

**ASSIGNMENT**

For good and valuable consideration, we,

Reinhold Bayerer, a citizen of Germany, residing at Viktoriastrasse 19  
59581 Warstein, Germany, Daniel Domes, a citizen of Germany, residing at Bahnhofstraße 32  
59602 Ruethen, Germany,

hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **Infineon Technologies AG**, having its principal place of business at Am Campeon 1-12, 85579 Neubiberg, Germany, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

filed on\_ US Serial No. /

entitled: **Low-Inductance Power Semiconductor Assembly**

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE: \_\_\_\_\_

Reinhold Bayerer

DATE: \_\_\_\_\_

2011-03-04

SIGNATURE: \_\_\_\_\_

Daniel Domes

DATE: \_\_\_\_\_

2011-03-04